

Title (en)  
GAS-PHASE DEPOSITION PROCESS

Title (de)  
GASPHASENABSCHEIDUNGSVERFAHREN

Title (fr)  
PROCÉDÉ DE DÉPÔT EN PHASE GAZEUSE

Publication  
**EP 3119921 A1 20170125 (FR)**

Application  
**EP 15711152 A 20150319**

Priority  
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Abstract (en)  
[origin: WO2015140261A1] The invention relates to a layer-deposition process, which includes: injecting a first reagent in gaseous phase into the deposition chamber (30) via a first injection path (40), and injecting a second gas-phase reagent into the deposition chamber (30) via a second injection path (50), the second injection path (50) being separate from the first injection path (40). The pressure in the deposition chamber (30) is greater than a predetermined value for the entire duration of the process. Said process is characterized in that the first reagent is fed into the deposition chamber (30) according to a first pulse sequence, and the second reagent is fed into the chamber according to a second pulse sequence. The first pulse sequence and the second pulse sequence are out of phase with one another.

IPC 8 full level  
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Citation (search report)  
See references of WO 2015140261A1

Citation (examination)  
• US 2004235191 A1 20041125 - HASEGAWA TOSHIO [JP]  
• JP 2010084156 A 20100415 - TOKYO ELECTRON LTD  
• JP 2006009152 A 20060112 - TOKYO ELECTRON LTD  
• US 2003108674 A1 20030612 - CHUNG HUA [US], et al

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Designated extension state (EPC)  
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DOCDB simple family (publication)  
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